National Semiconductor

# LM78L00 Series 3-Terminal Positive Voltage Regulators

# General Description

The LM78L00 series of 3-terminal positive voltage regulators employ internal current-limiting and thermal shutdown, making them essentially indestructible. If adequate heat sinking is provided, they can deliver up to 100 mA output current. They are intended as fixed voltage regulators in a wide range of applications including local (on-card) regulation for elimination of noise and distribution problems associated with single-point regulation. In addition, they can be used with power pass elements to make high current voltage regulators. The LM78L00, used as a Zener diode/resistor combination replacement, offers an effective output impedance improvement of typically two orders of magnitude, along with lower quiescent current and lower noise.

## Features

- Output current up to 100 mA
- $\blacksquare$  No external components
- $\blacksquare$  Internal thermal overload protection  $\blacksquare$  Internal short circuit current-limiting
- 
- Available in JEDEC TO-92
- $\blacksquare$  Output Voltages of 5.0V, 6.2V, 8.2V, 9.0V, 12V, 15V  $\blacksquare$  Output voltage tolerances of  $\pm 5%$  over the temperature range



June 1989

TL/H/10051 C1995 National Semiconductor Corporation TL/H/10051 National Semiconductor Corporation RRD-B30M115/Printed in U. S. A.



### Electrical Characteristics

0°C  $\leq$  T<sub>A</sub>  $\leq$  +125°C, V<sub>I</sub> = 10V, I<sub>O</sub> = 40 mA, C<sub>I</sub> = 0.33  $\mu$ F, C<sub>O</sub> = 0.1  $\mu$ F, unless otherwise specified (Note 1)



**Note 2:** Power Dissipation  $\leq 0.75W$ .

**Note 1:** The maximum steady state usable output current and input voltage are very dependent on the heat sinking and/or lead length of the package. The data<br>above represent pulse test conditions with junction temperatures



 $\Delta V_O/\Delta T$  Average Temperature  $\begin{vmatrix} 1_0 = 5.0 \text{ mA} \\ 0.8 \end{vmatrix}$  -0.8 mV/°C **Note 1:** The maximum steady state usable output current and input voltage are very dependent on the heat sinking and/or lead length of the package. The data<br>above represent pulse test conditions with junction temperatures

I<sub>Q</sub> Quiescent Current 2.1 5.5 mA  $\Delta I_Q$  Quiescent Current With Line  $12V \le V_1 \le 23V$  1.5 mA<br>Change With Load 1.0 mA  $\le I_Q \le 40$  mA 0.1 0.1  $N_{\text{O}}$  Noise  $T_{\text{A}} = 25^{\circ}$ C, 10 Hz  $\leq f \leq 100$  kHz 60  $\mu$ V  $\Delta V_1/\Delta V_O$  Ripple Rejection  $\left| f = 120$  Hz,  $12V \le V_1 \le 22V$ ,  $T_J = 25^{\circ}\text{C}$  39 45  $45$  $V_{\text{DO}}$  Dropout Voltage  $T_J = 25^{\circ}C$  1.7 1.7 V  $I_{\text{pk}}/I_{\text{OS}}$  Peak Output/Output  $I_J = 25^{\circ}\text{C}$  140 140 mA

Note 2: Power Dissipation  $\leq 0.75W$ .





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#### Design Considerations

The LM78L series regulators have thermal overload protection from excessive power, internal short-circuit protection which limits each circuit's maximum current, and output transistor safe-area protection for reducing the output current as the voltage across each pass transistor is increased. Although the internal power dissipation is limited, the junction temperature must be kept below the maximum specified temperature (125°C) in order to meet data sheet specifications. To calculate the maximum junction temperature or heat sink required, the following thermal resistance values should be used:



#### Thermal Considerations

The TO-92 molded package is capable of unusually high power dissipation due to the lead frame design. However, its thermal capabilities are generally overlooked because of a lack of understanding of the thermal paths from the semiconductor junction to ambient temperature. While thermal resistance is normally specified for the device mounted 1 cm above an infinite heat sink, very little has been mentioned of the options available to improve on the conservatively rated thermal capability.

An explanation of the thermal paths of the TO-92 will allow the designer to determine the thermal stress he is applying in any given application.

# The TO-92 Package

The TO-92 package thermal paths are complex. In addition to the path through the molding compound to ambient temperature, there is another path through the leads, in parallel with the case path, to ambient temperature, as shown in Figure <sup>1</sup>.

The total thermal resistance in this model is then:

 $\theta_{\text{JC}} + \theta_{\text{CA}} + \theta_{\text{JL}} + \theta_{\text{LA}}$ 

 $\theta_{JA} = \frac{(\theta_{JC} + \theta_{CA})(\theta_{JL} + \theta_{LA})}{\theta_{A} + \theta_{A} + \theta_{A} + \theta_{A} + \theta_{A} + \theta_{A} + \theta_{A} + \theta_{A}}$ 

Where:

- $\theta_{\text{JC}}$  thermal resistance of the case between the requlator die and a point on the case directly above the die location.
- $\theta_{CA}$  thermal resistance between the case and air at ambient temperature.
- $\theta_{\text{JL}}$  thermal resistance from regulator die through the input lead to a point  $1/16$  inch below the regulator case.
- $\theta_{LA}$  total thermal resistance of the input/output ground leads to ambient temperature.
- $\theta_{\text{JA}}$  = junction to ambient thermal resistance.



#### Methods of Heat Sinking

With two external thermal resistances in each leg of a parallel network available to the circuit designer as variables, he can choose the method of heat sinking most applicable to his particular situation. To demonstrate, consider the effect of placing a small 72 °C/W flag type heat sink, such as the Staver F1-7D-2, on the LM78L00 molded case. The heat sink effectively replaces the  $\theta_{CA}$  (Figure 2) and the new thermal resistance,  $\theta'$ <sub>JA</sub>, equals 145 °C/W (assuming, 0.125 inch lead length).

The net change of 15 °C/W increases the allowable power dissipation to 0.86W with a minimal inserted cost. A still further decrease in  $\theta_{JA}$  could be achieved by using a heat sink rated at 46 °C/W, such as the Staver FS-7A. Also, if the case sinking does not provide an adequate reduction in total  $\theta_{JA}$ , the other external thermal resistance,  $\theta_{LA}$ , may be reduced by shortening the lead length from package base to mounting medium. However, one point must be kept in mind. The lead thermal path includes a thermal resistance,  $\theta_{\text{SA}}$ , from the leads at the mounting point to ambient, that is, the mounting medium.  $\theta_{\text{LA}}$  is then equal to  $\theta_{\text{LS}} + \theta_{\text{SA}}$ . The new model is shown in Figure 2.

In the case of a socket,  $\theta_{SA}$  could be as high as 270 °C/W, thus causing a net increase in  $\theta_{JA}$  and a consequent decrease in the maximum dissipation capability. Shortening the lead length may return the net  $\theta_{JA}$  to the original value, but lead sinking would not be accomplished.

In those cases where the regulator is inserted into a copper clad printed circuit board, it is advantageous to have a maximum area of copper at the entry points of the leads. While it would be desirable to rigorously define the effect of PC board copper, the real world variables are too great to allow anything more than a few general observations.

(1)





